

Schottky Barrier Diode Silicon Epitaxial

CCS15F40

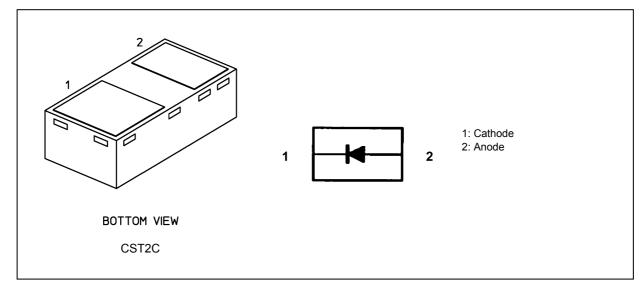
1. Applications

High-Speed Switching

2. Features

- (1) High average rectified current
- (2) Low reverse current: $I_R(2) = 8 \ \mu A$ (typ.) at $V_R = 40 \ V$

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25 \text{ °C}$)

Characteristics	Symbol	Note	Rating	Unit
Reverse voltage	V _R		40	V
Average rectified current	I _O	(Note 1)	1.5	А
Non-repetitive peak forward surge current	I _{FSM}	(Note 2)	5	А
Power dissipation	PD	(Note 1)	900	mW
Junction temperature	Tj		150	°C
Storage temperature	T _{stg}		-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

(25.4 mm \times 25.4 mm \times 1.6 mm, Cu Pad: 645 mm²)

Note 2: Measured with a 10 ms pulse.

5. Electrical Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V _F (1)	I _F = 500 mA	_	0.40	0.45	V
	V _F (2)	I _F = 1 A	_	0.50	0.55	
	V _F (3)	I _F = 1.5 A	_	0.59	0.64	
Reverse current	I _R (1)	V _R = 10 V		5	15	μA
	I _R (2)	V _R = 40 V		8	25	
Total capacitance	Ct	V _R = 0 V, f = 1 MHz	_	130	_	pF

6. Marking

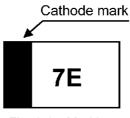


Fig. 6.1 Marking

Marking Code	Part Number		
7E	CCS15F40		

7. Usage Considerations

• Schottky barrier diodes (SBDs) have reverse leakage greater than other types of diodes. This makes SBDs more susceptible to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.

Note 1: Mounted on an FR4 board.

8. Land Pattern Dimensions (for reference only)

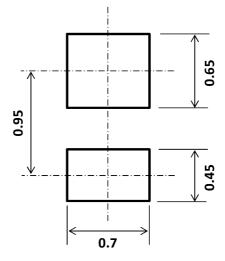
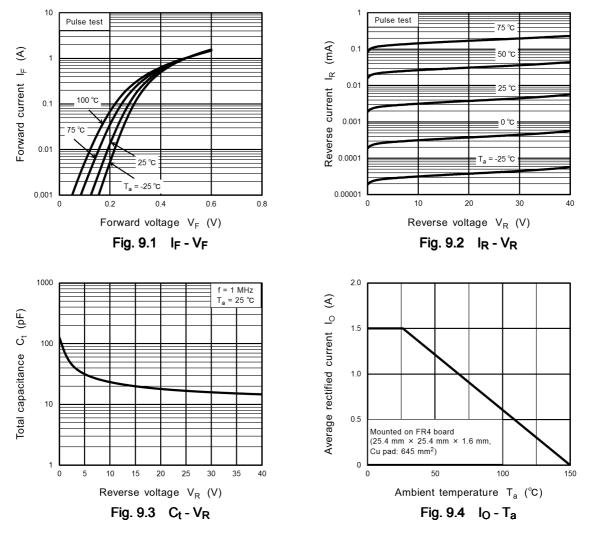


Fig. 8.1 Land Pattern Dimensions for Reference Only (Unit: mm)

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9. Characteristics Curves (Note)

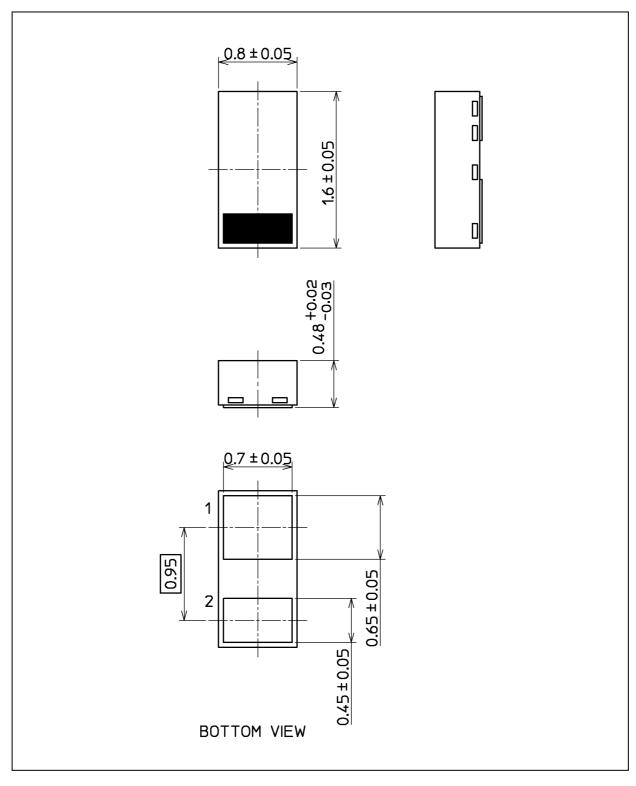


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 1.9 mg (typ.)

Package Name(s)

Nickname: CST2C

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